

Title (en)

REACTION RESINS FOR POTTING PRESSURE-SENSITIVE ELECTRONIC COMPONENTS.

Title (de)

REAKTIONSHARZE ZUM VERGIESSEN VON DRUCKEMPFLINDLICHEN ELEKTRONISCHEN BAUELEMENTEN.

Title (fr)

RESINES DE REACTION POUR L'ENROBAGE DE COMPOSANTS ELECTRONIQUES SENSIBLES A LA PRESSION.

Publication

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Application

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Priority

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- DE 4211250 A 19920403

Abstract (en)

[origin: WO9320585A1] For the potting of pressure-sensitive electronic components, the invention proposes that an epoxy/anhydride reaction-resin system with a high glass-transition temperature be modified with finely dispersed silicon-rubber particles and a vitreous fused silica filler with the optimum particle-size distribution in order to improve the modulus of elasticity, crack resistance and resistance to changes in temperature, while maintaining the resistance to moisture and chemicals at the same level.

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IPC 8 full level

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